

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Cancelled)
2. (Currently Amended) A bonded wafer having a base wafer wherein a back surface of ~~it's~~ the base wafer is chemically etched and a chamfered part of the base wafer is subjected to chamfering and mirror finishing to form a mirror surface, and on the chemically etched back surface, a maximal depth of pits is 6  $\mu\text{m}$  or less and an average value of waviness is 0.04  $\mu\text{m}$  or less, wherein the base wafer is bonded to a bond wafer.
3. (Currently Amended) A bonded wafer having a base wafer wherein a power spectrum density on a back surface of the base wafer is 0.5 to 10  $\mu\text{m}^3$  as measured by waviness having a wavelength of 10 mm, wherein the base wafer is bonded to a bond wafer.
4. (Currently Amended) A bonded wafer having a base wafer wherein at least a back surface and a chamfered part of the base wafer are mirror surface and the chamfered part of the base wafer is subjected to chamfering and mirror finishing, wherein the base wafer is bonded to a bond wafer.